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Santa Clara, California—August 29, 2002—Pac Tech USA Packaging Technologies Inc. will complete construction of its 2000 ft^2 clean room by November 2002. According to Ron Blankenhorn, President of Pac Tech USA, this facility will serve to demonstrate Pac Tech Germany designed and built production and prototype equipment. Dr. Thorsten Teutsch, the new CTO of Pac Tech USA, says that Pac Tech USA already accepts orders for Electroless Ni/Au under-bump metallization process using our parent company, Pac Tech Germany; he will direct the transfer of the process from Pac Tech Germany to Pac Tech USA. Dr. Teutsch states that the new PacLine 2000 A50 was build for handling a volume wafer bumping capacity of 600,000 200mm wafers and is 300mm capable. ISO 9001 certification of the process is scheduled for Q3/2003 according to Dr. Teutsch.

By September, Pac Tech USA will have a showroom and application laboratory installed for local demonstration of solder balling services using Pac Tech's Solder Ball Bumper SB^2. This unique machine is capable to perform a fluxless solder jetting process (10 balls/sec). Beside fast prototyping and repair features, the SB^2 is the ultimate solution for solder bumping of Flip Chip, BGA, MEMs, HDD, and Optical Devices. Pac Tech also announces that Pac Tech USA Inc. will exhibit at the IMAPS 2002 in Denver, CO from September 4-6, at booth 516.